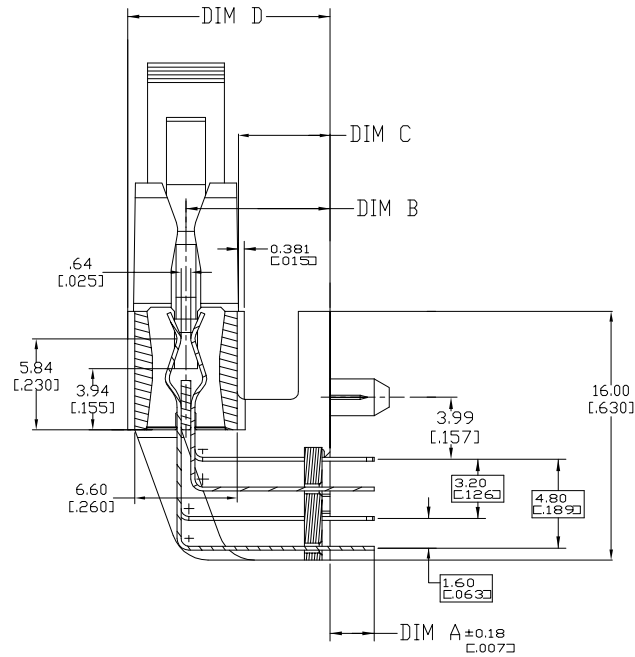
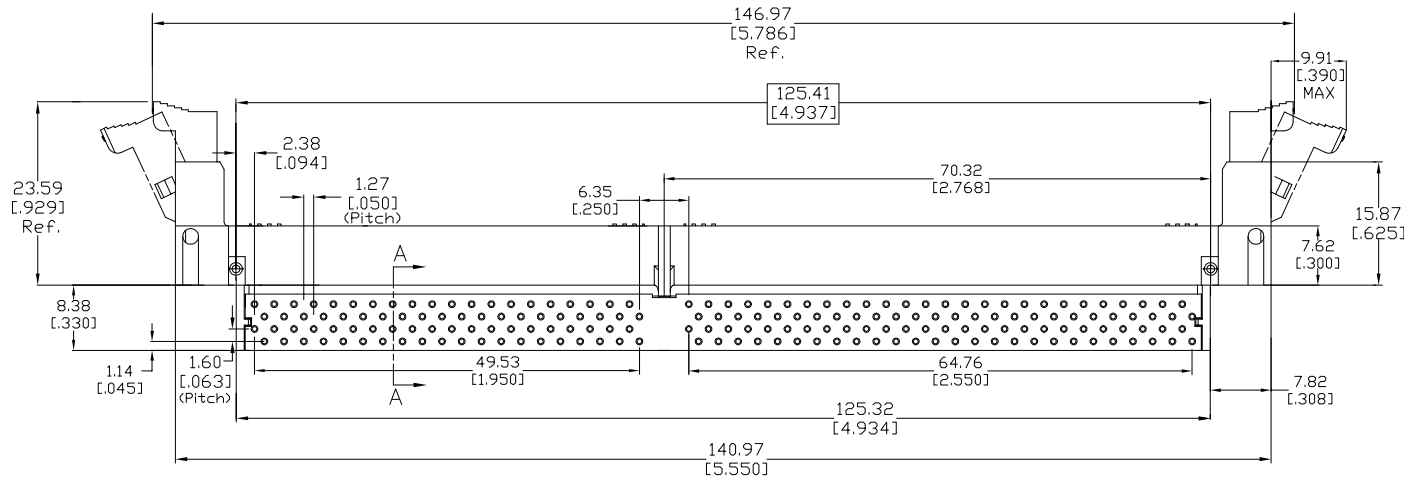


LOC		REV		REVISIONS	
GP	0	NO	DATE	BY	APP
B		REVISED PER ECR-07-018297	3AUG07	K.C.S.Y	

NOTES:

- ⚠ MATERIAL:
HOUSING:
HIGH TEMPERATURE NYLON
CONTACT:
PHOSPHOR BRONZE
- ⚠ FINISH:
CONTACT AREA:
0.000076[0.000003] MIN THICK GOLD FLASH OVER
0.000510[0.000020] MIN THICK PALLADIUM NICKEL
OR 0.00076[0.000030] MIN. THICK GOLD OVER
0.00381[0.000150] MIN. THICK NICKEL UNDERPLATE.
- SOLDDERTAIL:
0.00381[0.000150] MIN THICK MATTE TIN OVER
0.00064[0.000025] MIN THICK NICKEL
- ⚠ MODULE BOARD PADS:
FOR OPTIMUM PERFORMANCE, PADS SHOULD BE SMOOTH AND FLAT
PADS TO BE PLATED WITH:
0.00102[0.000040] MIN THICK GOLD OVER
0.00127[0.000050] MIN THICK NICKEL
- ⚠ CONNECTOR MANUFACTURED WITH LUBRICANT
ADDED TO THE CONTACT INTERFACE.



SECTION A-A
SCALE 6:1

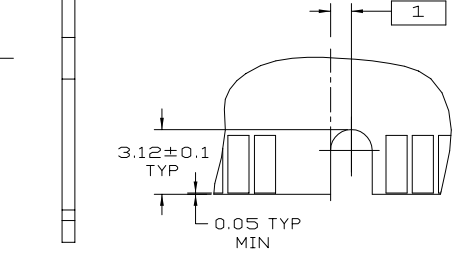
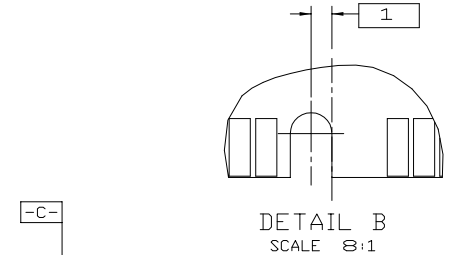
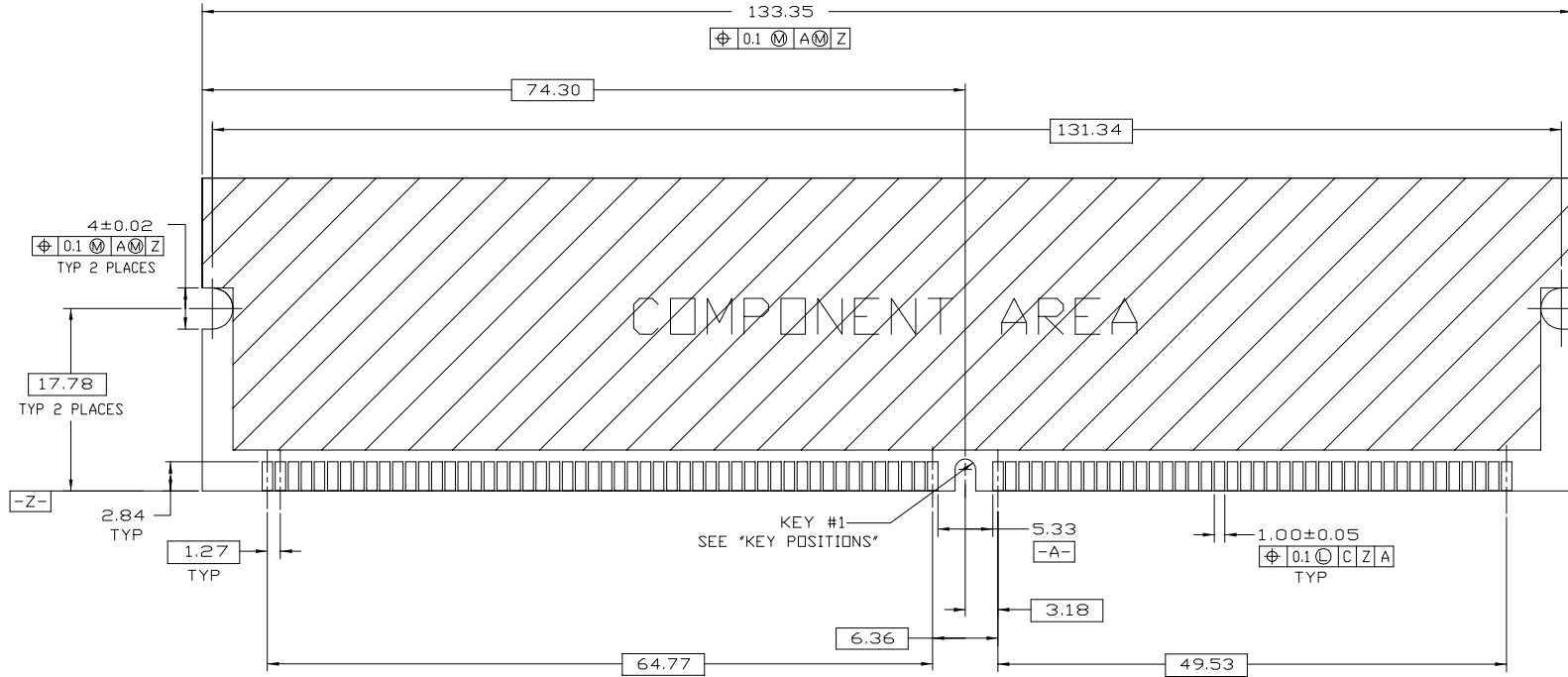
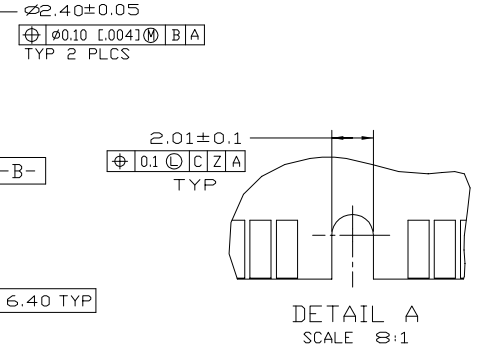
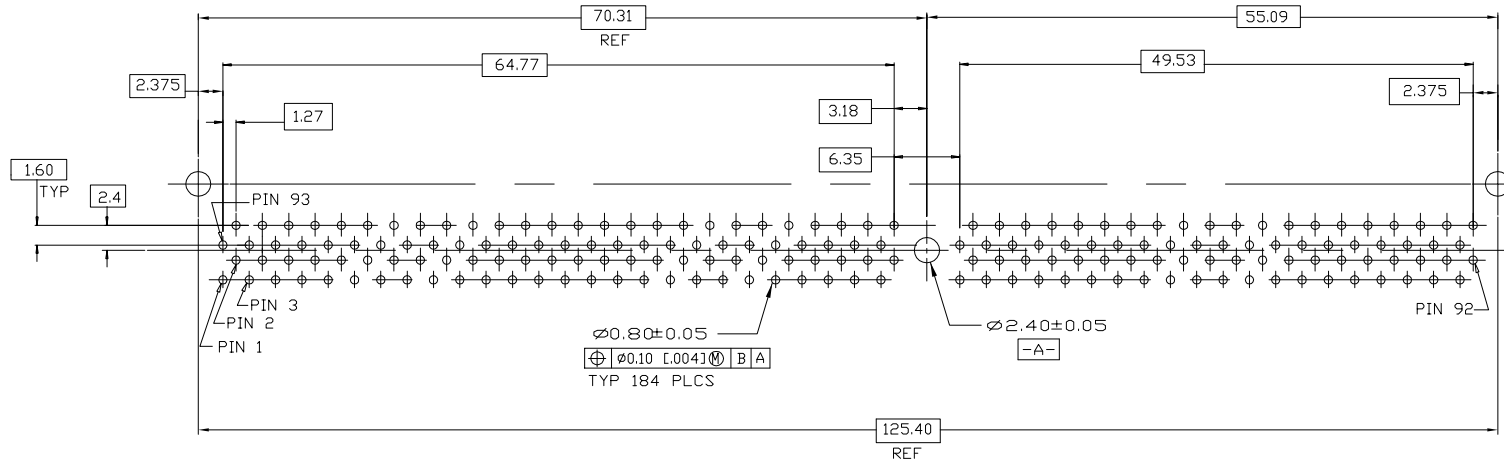
10.80[.425]	3.68[.145]	7.11[.280]	3.18[.125]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-7	⚠
10.80[.425]	3.68[.145]	7.11[.280]	2.84[.112]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-6	⚠
12.95[.510]	5.83[.230]	9.27[.365]	3.18[.125]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-5	⚠
12.95[.510]	5.83[.230]	9.27[.365]	3.18[.125]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-4	
12.95[.510]	5.83[.230]	9.27[.365]	3.68[.145]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-3	
12.95[.510]	5.83[.230]	9.27[.365]	2.84[.112]	DETAIL B	184 POS. DDR DRAM, 2.5 VOLT	5390447-1	
DIM D	DIM C	DIM B	DIM A	KEY #1	PART DESCRIPTION	PART NUMBER	

DIMENSIONS:		DRAWING APPROVALS:		DRAWING INFORMATION:	
mm [INCHES]		DATE	BY	NO.	REV.
0 P.C.	± .005	08/07/07	S. WAITMAN	5390447	1
1 P.C.	± 0.3		H. YEOMANS		
2 P.C.	± 0.05				
3 P.C.	± 0.010				
4 P.C.	± .1				
MATERIAL	FINISH	WEIGHT	SCALE	SHEET	REV
⚠	⚠	-	1:1	1	2

DIMENSIONS: mm [INCHES]
 DRAWING APPROVALS: DATE BY NO. REV.
 DRAWING INFORMATION: NAME PRODUCT SPEC APPLICATION SPEC SIZE CASE CODE DRAWING NO. WEIGHT
 MATERIAL: ⚠ FINISH: ⚠ WEIGHT: - SCALE: 1:1 SHEET: 1 OF 2 REV: 2
 CUSTOMER DRAWING: A1 00779 C-5390447

LOC	DISP	REVISIONS			
GP	0	REV	DATE	BY	APP'D
		1			
		SEE SHEET 1			

RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



KEY POSITIONS

RECOMMENDED MODULE LAYOUT

SEE JEDEC SPEC. MO-206 FOR COMPLETE MODULE DETAILS
 1.27 ± 0.10 THICK ACROSS CONTACT PADS
 SCALE 4:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRG: S. WATMAN	RELECO: Tyco Electronics Corporation
DIMENSIONS: mm (INCHES)		CHK: M. YEOMANS	Harrisburg, Pa 17105-3608
MATERIAL: Δ		APP: M. YEOMANS	NAME: SOCKET, DIMM, DRO, RIGHT ANGLE
FINISH: Δ		APPLICATION SPEC: -	184 POSITION, 1.60mm CONTACT PITCH
WEIGHT: -		SIZE: A1	LEAD-FREE
CUSTOMER DRAWING		DRAWING NO: 00779	REV: 2
SCALE: 1:1		DWG NO: 5390447	REV: 2